

P-Channel 30V (D-S) MOSFET
GENERAL DESCRIPTION

The ME9435 is the P-Channel logic enhancement mode power field effect transistors, using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone, notebook computer power management and other battery powered circuits, and in-line power loss that are needed in a very small outline surface mount package.

FEATURES

- $R_{DS(ON)} \leq 60m\Omega$ @ $V_{GS} = 10V$
- $R_{DS(ON)} \leq 90m\Omega$ @ $V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

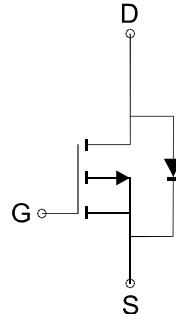
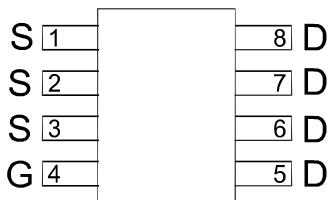
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

PIN CONFIGURATION

(SOP-8)

Top View



P-Channel MOSFET

Ordering Information: ME9435 (Pb-free)

ME9435-G (Green product-Halogen free)

Absolute Maximum Ratings ($T_A=25^\circ C$ Unless Otherwise Noted)

| Parameter | Symbol | Maximum Rating | Unit |
|--|----------|----------------|------|
| Drain-Source Voltage | V_{DS} | -30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current | I_D | -5.1 | A |
| | | -4.1 | |
| Pulsed Drain Current | I_{DM} | -20 | A |
| Maximum Power Dissipation | P_D | 2.5 | W |
| | | 1.6 | |
| Operating Junction Temperature | T_J | -55 to 150 | °C |
| Junction-to-Ambient Thermal Resistance | R_{JA} | 50 | °C/W |

*The device mounted on 1in² FR4 board with 2 oz copper



P-Channel 30V (D-S) MOSFET
Electrical Characteristics (TA=25°C Unless Otherwise Specified)

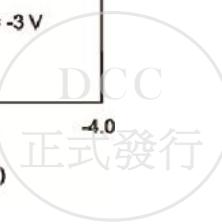
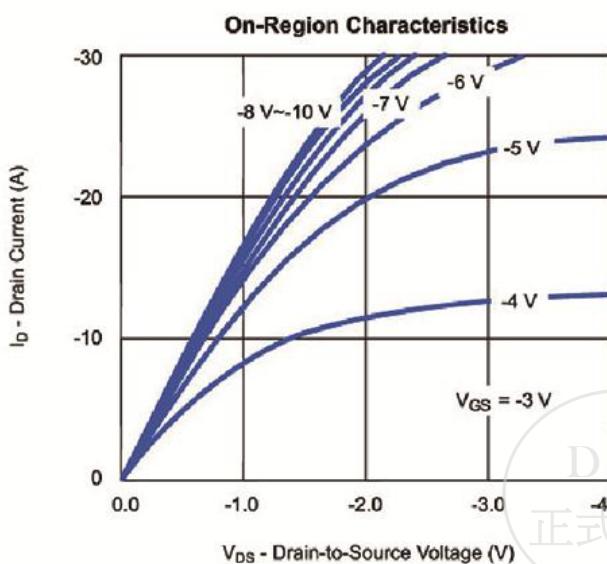
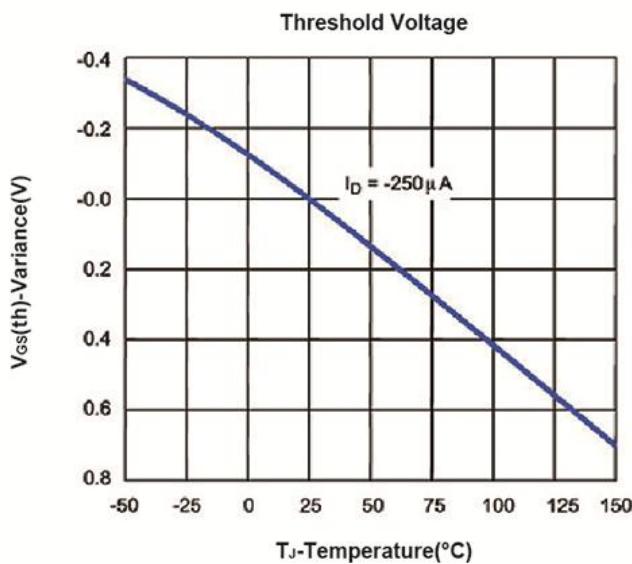
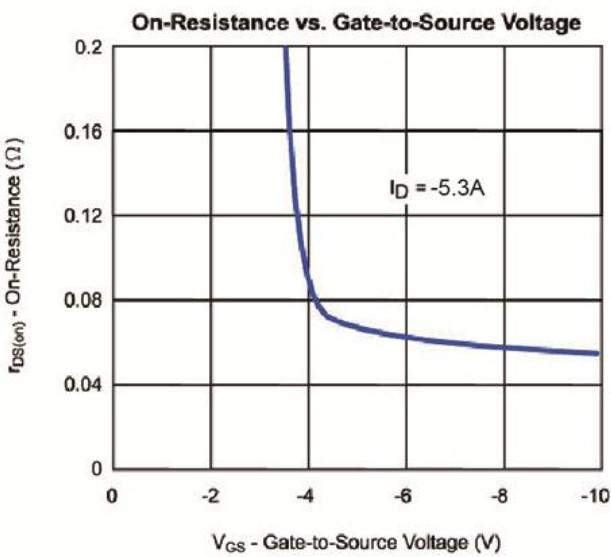
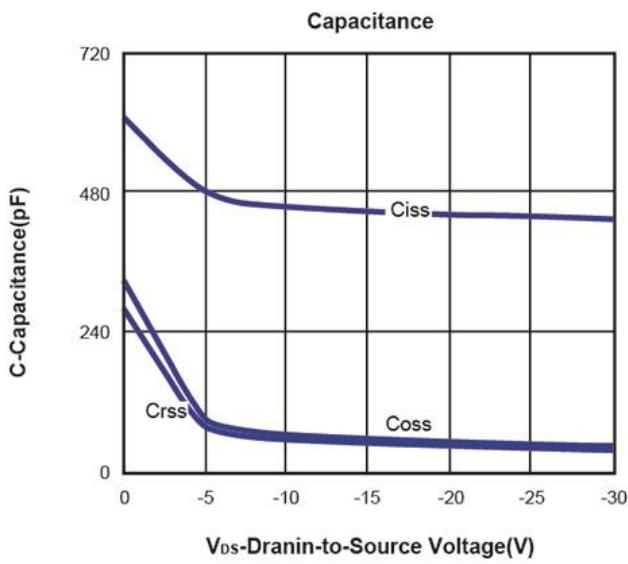
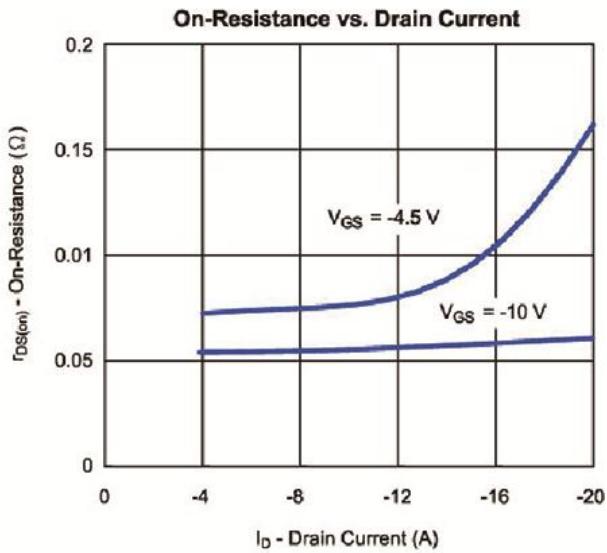
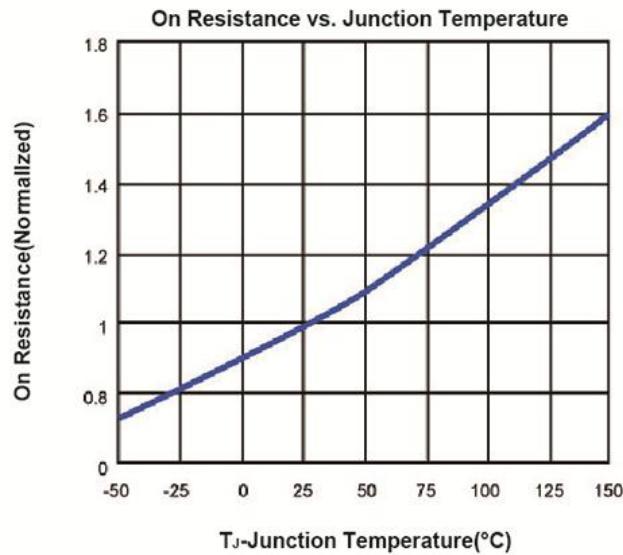
| Symbol | Parameter | Limit | Min | Typ | Max | Unit |
|---------------------|---------------------------------|---|-----|------|------|------|
| STATIC | | | | | | |
| BVDSS | Drain-Source Breakdown Voltage | V _{GS} =0, I _D =-250 μA | -30 | | | V |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =-250 μA | -1 | | -3 | V |
| I _{GSS} | Gate Body Leakage | V _{DS} =0V, V _{GS} =±20V | | | ±100 | nA |
| I _{bss} | Zero Gate Voltage Drain Current | V _{DS} =-30V, V _{GS} =0V | | | -1 | μA |
| R _{DSON} | Drain-Source On-Resistance | V _{GS} =-10V, I _D = -5.3A | | 50 | 60 | mΩ |
| | | V _{GS} =-4.5V, I _D = -4.2A | | 70 | 90 | |
| V _{SD} | Diode Forward Voltage | I _S =-5.3A, V _{GS} =0V | | -0.9 | -1.2 | V |
| DYNAMIC | | | | | | |
| Q _g | Total Gate Charge | V _{DS} =-15V, V _{GS} =-10V, I _D =-5.3A | | 13 | | `pF |
| Q _g | Total Gate Charge | V _{DS} =-15V, V _{GS} =-4.5V, I _D =-5.3A | | 6.2 | | |
| Q _{gs} | Gate-Source Charge | | | 3.5 | | |
| Q _{gd} | Gate-Drain Charge | | | 2 | | |
| C _{iss} | Input capacitance | V _{DS} =-15V, V _{GS} =0V, f=1MHz | | 446 | | nC |
| C _{oss} | Output Capacitance | | | 55 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 50 | | |
| t _{d(on)} | Turn-On Delay Time | V _{DD} =-15V, R _L =15Ω I _D =-1A, V _{GEN} =-10V R _G =6Ω | | 29 | | ns |
| t _r | Turn-On Rise Time | | | 13 | | |
| t _{d(off)} | Turn-Off Delay Time | | | 39 | | |
| t _f | Turn-Off Fall Time | | | 5.5 | | |

Notes: a. Pulse test; pulse width ≤ 300us, duty cycle≤ 2%

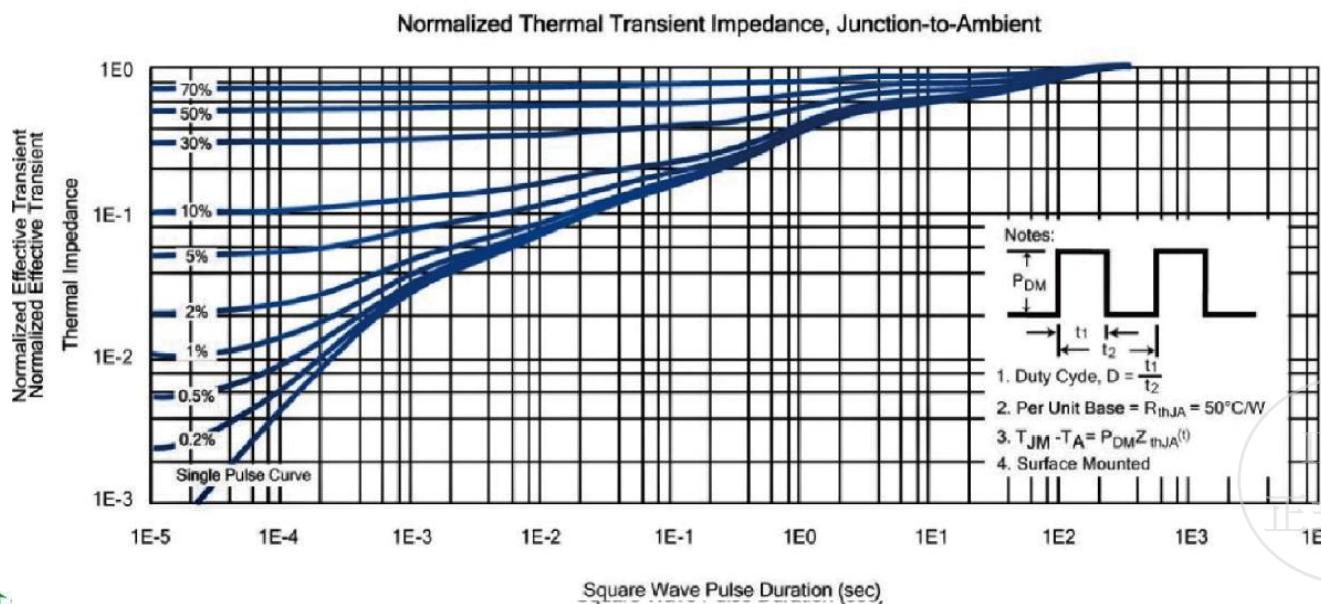
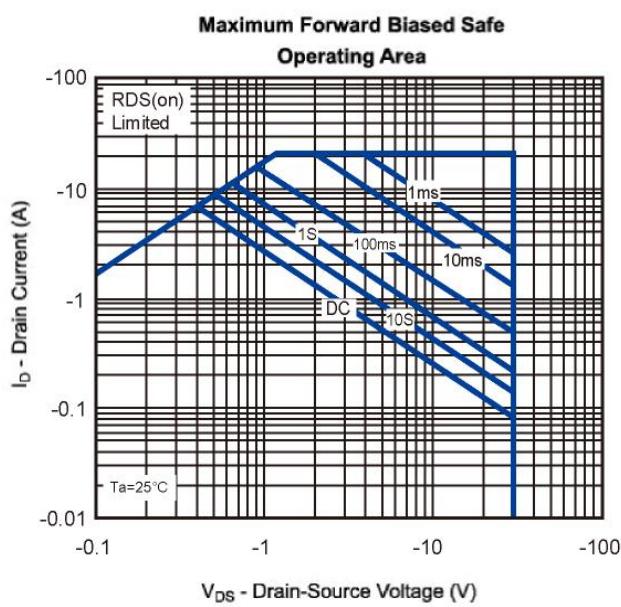
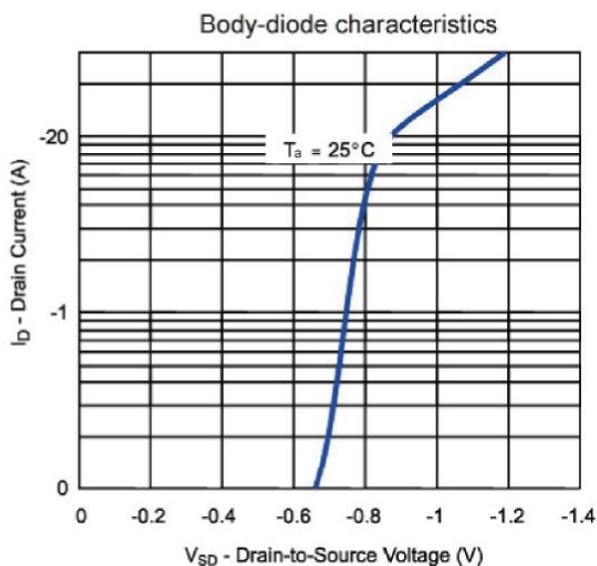
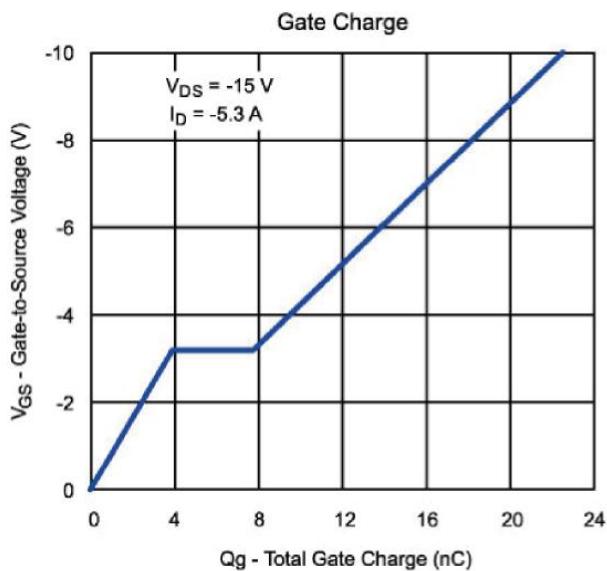
b. Matsuki Electric/ Force mos reserves the right to improve product design, functions and reliability without notice.



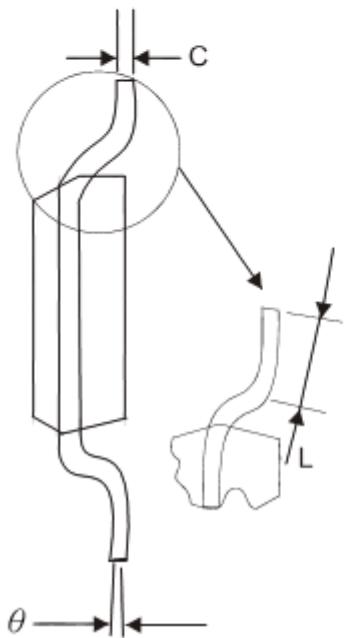
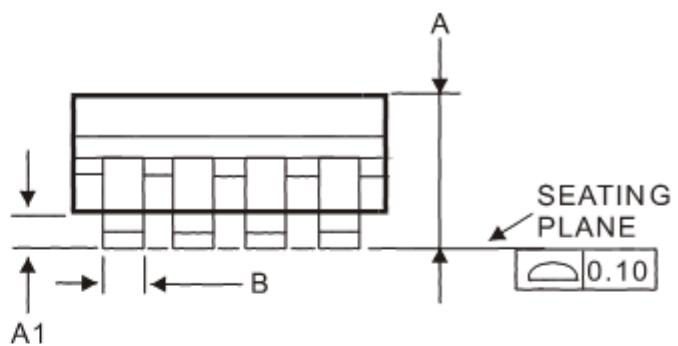
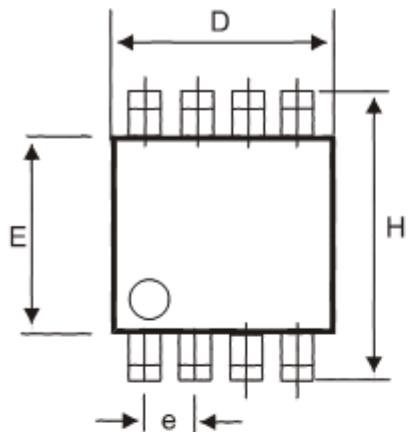
Typical Characteristics ($T_J = 25^\circ\text{C}$ Noted)



Typical Characteristics (T_J =25°C Noted)



SOP-8 Package Outline



| DIM | MILLIMETERS (mm) | |
|----------|------------------|------|
| | MIN | MAX |
| A | 1.35 | 1.75 |
| A1 | 0.10 | 0.25 |
| B | 0.35 | 0.49 |
| C | 0.18 | 0.25 |
| D | 4.80 | 5.00 |
| E | 3.80 | 4.00 |
| e | 1.27 BSC | |
| H | 5.80 | 6.20 |
| L | 0.40 | 1.25 |
| θ | 0° | |

